

Optimization Techniques for Low Power VLSI Design

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Abstract- With shrinking technology, as power density (measured in watts per square millimetre) is raising at an alarming rate, power management is becoming an important aspect for almost every category of design and application. Reducing power consumption and over all on chip power management are the key challenges in deep sub micro meter nodes due to increased complexity.

Power management needs to be considered at very early design stages. Also low-power techniques should to be employed at every design stage, from RTL (Register Transfer Level) to GDSII. This survey paper describes the various strategies, methodologies and power management techniques for low power VLSI circuits. Future challenges that must be met by designers to designs low power high performance circuits are also discussed. State-of-the-art optimization methods at different abstraction levels that target design of low power digital VLSI circuits are surveyed.

Keywords— Optimization, low power, power dissipation, power management

I. INTRODUCTION

In the past decades, the main focus of VLSI designers were performance, area and design cost. Power consumption was mostly of only secondary importance relatively. However, this trend has begun to change and, with major priority, power consumption is given comparable importance to speed and area.

The advantage of utilizing combination of low-power design techniques in conjunction with low-power components is more valuable now. Heat generation in high-end computer products limits the feasible IC packaging and performance of circuits and thus increases the packaging and cooling costs. Heat pumped into the room, the electricity consumed and the

office noise diminishes with low power VLSI chipset. Requirements for lower power consumption continue to increase significantly as components become battery-powered, compact and require complex functionality. At sub micro meter process nodes, leakage power consumption has joined switching activity as a primary power management concern.

II. RELATED CONCEPTS

A. Power Dissipation Basics

Total power consumption by a CMOS device is given by,

$$P_{\text{dissipation}} = P_{\text{static}} + P_{\text{dynamic}} + P_{\text{short circuit}} \dots \dots \dots (a)$$

Dynamic power or switching power is power dissipated during charging or discharging of capacitors and is described below [1] [2].

$$P_{\text{dyn}} = CL * V_{\text{dd}}^2 * \alpha * f \dots \dots \dots (b)$$

Where CL : Load Capacitance is a function of fan-out, wirelength, and transistor size,

V_{dd}: Supply Voltage, which has been dropping with successive process nodes,

α : Activity Factor

f :Clock Frequency, which is increasing at each successive process node.

Short-circuit power dissipation occurs due to short circuit current(I_{sc}) that flows when both the NMOS and PMOS devices are simultaneously 'on' for a short time duration and is given by the below equation,

$$P_{\text{short-circuit}} = I_{\text{sc}} * V_{\text{dd}} * f \dots \dots \dots (c)$$

Static power dissipation is due to reverse saturation, sub-threshold and leakage current and occurs especially when the device is in idle mode. It is given by the below equation.
 $P_{static} = f(V_{dd}, V_{th}, W/L) \dots\dots\dots(d)$

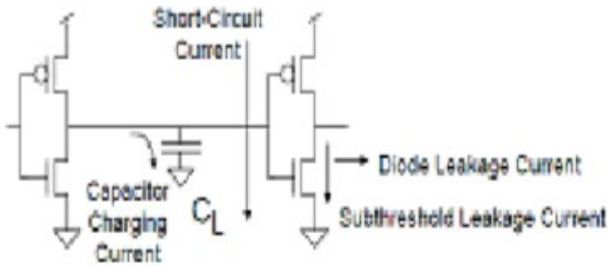


Figure 1: Power Dissipation in CMOS

where V_{th} is threshold voltage, 'W' is transistor width and 'L' is transistor length

Figure-1 shows the various components responsible for power dissipation in CMOS.

B. Low Power Strategies

Low power designs strategies at various abstraction levels are listed in table 1.

Table -1, Strategies for low power designs

| Design Level | Strategies |
|------------------------|---|
| Operating System Level | Portioning, Power down |
| Software level | Regularity, locality, concurrency |
| Architecture level | Pipelining, Redundancy, data encoding |
| Circuit /Logic level | Logic styles, transistor sizing and energy recovery |
| Technology Level | Threshold reduction, multi threshold devices |

Effective power management is possible by using the different strategies at various levels in VLSI Design process. So designers need an intelligent approach for optimizing power consumptions in designs.

C. Power Optimization Techniques

Table-2 describes low power techniques used at different levels [3][4].

Table 2: Few low power techniques used today

| Traditional Techniques | Dynamic Power Reduction | Leakage power reduction | Other Power reduction Techniques |
|---------------------------|----------------------------|-----------------------------------|---------------------------------------|
| Clock Gating | Clock Gating | Minimize usage of low V_t cells | Multi Oxide devices |
| Power Gating | Power Efficient Techniques | Power Gating | Minimize capacitance by custom design |
| Variable Frequency | Variable Frequency | Back Biasing | Power efficient circuits |
| Variable Voltage Supply | Variable Voltage Supply | Reduce Oxide Thickness | |
| Variable Device Threshold | Variable Island | Use Fin FET | |

III. POWER MANAGEMENT STRATEGIES

Effective power management involves selection of the right technology, the use of optimized libraries, IP (intellectual property), and design methodology [3]. We survey state-of-art optimization methods at different abstraction levels.

Inventory Management), POS (Point of Service), ReSA (Retail Sales Audit) and RIB (Retail Integration Bus).

A. Technology Level

Proper technology selection is one of the key aspects of power management [3]. The goal of each technology advancement is to improve performance, density, and power consumption more generalized form of scaling is used.

i. Using Multi-threshold Voltage

Multi-threshold CMOS (MTCMOS) is a method to reduce standby leakage current in the circuit, with the use of a high threshold apply to the MOS device to de-couple the logic either from the supply or ground during long idle periods, or sleep states. The Figure 2 shows a MTCMOS circuit, where the logic block is constructed using low threshold devices and the Power/ground supply given to the gate of the of the MTCMOS is a gated by high threshold header/footer switch[5].

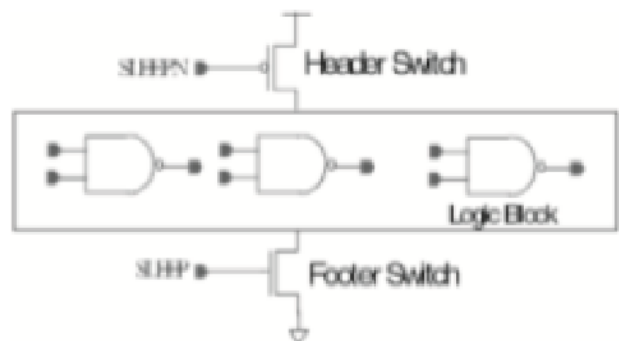


Figure 2: MTCMOS Circuit



ii. Multi-supply Voltage (Voltage Islands)

Multi-Vdd is an effective method to reduce both leakage and dynamic power, by assigning different supply voltages to cells according to their timing criticality. In a multi-Vdd design, cells of different supply voltage are often grouped into small number of voltage islands (each having a single supply voltage), in order to avoid complex power supply system and excessive amount of level shifters. Low power design methodology which manages power, timing and design cost by using multi-Vdd and voltage islands has to be developed [5] [6].

iii. Dynamic Voltage and Frequency Scaling

It allows host to dynamically switch its CPU frequency depending on its load requirement. CPU utilization is continuously monitored with the DVFS algorithm determining any necessary adjustment to the CPU's frequency with the goal being to run the CPU at a lower frequency so that it consumes less power. Example: If 2 GHz CPU is sitting at 30% utilization then DVFS will reduce the frequency of the CPU so it will operate nearer to its 600MHz frequency requirement including enough headroom to accommodate a sudden increase in CPU requirement[7][8][9][10].

B. Circuit Level

Transistor Sizing: The length-to-width ratio of transistors determines the driving strength and speed. On upsizing, gate delay decreases, however, power dissipated in the gate increases. Further, the delay of the fanin gates increases because of increased load capacitance. Given a delay constraint, finding an appropriate sizing of transistors that minimizes power dissipation is a computationally difficult problem. A typical approach to the problem is to compute the slack at each gate in the circuit, where the slack of a gate corresponds to how much the gate can be slowed down without affecting the critical delay of the circuit.

C. Logic Level

We survey optimizations that reduce switching activity power of logic-level combinational and sequential circuits in- this section.

i. Combinational

Combinational logic optimization has traditionally been decomposed into two phases: technology-independent optimization and technology-dependent optimization. In the first phase logic equations are manipulated to reduce area, delay or power dissipation. In the second phase the equations are mapped to a particular technology library using technology mapping algorithms, again optimizing for area, delay or power. For a comprehensive treatment of combinational logic synthesis methods targeting area and delay [11].

Don't-care Optimization: Any gate in a combinational circuit has an associated controllability and observability don't-care set. The controllability don't-care set corresponds to the input combinations that never occur at the gate inputs. The observability don't-care set corresponds to collections of input combinations that produce the same values at the circuit outputs. Methods to reduce circuit area and improve delay exploiting don't-care sets have been presented in [12]. The power dissipation of a gate is dependent on the probability of the gate evaluating to a 1 or a 0. This probability can be changed by utilizing the don't-care sets. A method of don't-care optimization to reduce switching activity and therefore power dissipation was presented in [13]. This method was improved upon in [14] where the effect of don't-care optimization of a particular gate on the gates in its transitive fanout is considered.

Path Balancing: The delays of paths that converge at each gate in the circuit should be nearly equal to reduce spurious switching activity. By selectively adding unit-delay buffers to the inputs of gates in a circuit, the delays of all paths in the circuit can be made equal. This addition will not increase the critical delay of the circuit, and will effectively eliminate spurious transitions. However, the addition of buffers increases capacitance which may offset the reduction in switching activity. Design of a multiplier with transition reduction circuitry that accomplishes glitch reduction by path balancing is described in [15].

Factorization: Factorization of logical expressions is primary means of technology-independent optimization. Example, the expression $ac + ad + bc + bd$ can be factored into $(a + b)(c + d)$ reducing transistor count considerably. Modified kernel extraction methods that target switching activity power are described in [16].

ii. Technology Mapping

Optimized logic equations are mapped into a target library that contains optimized logic-gates in the chosen technology. A typical library will contain hundreds of gates with different transistor sizes. Modern technology mapping methods use a graph covering formulation, originally presented in [17], to target area and delay cost functions. The graph covering formulation of [17] has been extended to the power cost function.

iii. Sequential

Encoding State encoding for minimal area is a well-researched problem [18]. These methods have to be modified to target a power cost function, namely, weighted switching activity. Methods to encode State Transition Graphs to produce two-level and multilevel implementations with minimal power are described in [16] and [19]. Encoding to reduce switching activity in datapath logic has also been the subject of attention. A method to minimize the switching on buses is proposed in [20].

Retiming: Retiming [21] is a well-known optimization method that repositions the flip-flops in a synchronous sequential circuit so as to minimize the required clock period. A retiming method that targets the power dissipation of a sequential circuit is described in [22].

Clock Tree Optimization and Clock Gating: Rapid scaling has two profound impacts. First, it enables much higher degree of on-chip integration. The number of transistors per chip will increase by more than 2x per generation according to Moore's law. Second, Interconnect has become the dominating factor in determining circuit performance and reliability in deep submicron designs. The interconnect design will play the most critical role in achieving the projected clock frequencies. Clock distribution is crucial for timing and design convergence. Minimum delay/power, zero skew buffer insertion/ sizing and wire-sizing problems have long been considered intractable. Most of the power is consumed due to the high clock frequency used for operating the device. Portions of the clock tree that are not being used at any particular time can be disabled to save the power.

iv. Pin Swapping

Some cells can have input pins that are symmetric with respect to the logic function (for example, in a 2-input NAND gate the two input pins are symmetric), but have different capacitance values. Power can be reduced by assigning a higher switching rate net to a lower capacitance pin

Power minimization techniques like pin swapping is also called as local transformations [23]. They are applied on gate netlists, and focus on nets with large switched capacitance. Example: Consider 4 input NAND gate with different capacitance value at the pin as show in the Figure 3. a high activity net is connected to the pin no 4 that is pin "d" which has the minimum input capacitance. To achieve the minimum input capacitance pin swapping is done between the pins "a" and "d".



Figure 3: Nand Gate

v. Power Shutoff or Power Gating

Power gating is the technique used to temporarily turn off the sub blocks to reduce the overall leakage power of the chip. This temporary shutdown time can also call as "low power mode" or "inactive mode". When circuit blocks are required for operation once again they are activated to "active mode". These two modes are switched at the appropriate time and in the suitable manner to maximize power performance while minimizing impact to performance. Thus goal of power gating is to minimize leakage power by temporarily cutting power off to selective blocks that are not required in that mode.

D. Architectural and Behavioural level

i. Memory Splitting

Off-chip memory accesses are very expensive power wise. Reordering of bus transactions (to minimize signal transitions) can reduce overall energy consumption. Number of bit flips on the memory bus can be reduced by proper data encoding or by scheduling bus transactions in the order in which they would cause the minimal signal changes.

ii. Operand Isolation

Redundant operations are identified and special isolation circuitry is used to prevent switching activity from propagating into a module whenever it is about to perform a redundant operation.

E. System And Software Level

An increasing fraction of applications are being implemented as embedded systems consisting of a hardware and a software components. As major part of the functionality is in the form of instructions as opposed to gates, Hardware-based power estimation and optimization approaches are not completely applicable here. This motivates the need to consider the power consumption in micro- processors from the point of view of software. Instruction-level power models are developed successfully for some commercial CPUs. Given the ability to evaluate programs in terms of power/energy costs, it is possible to search the design space in software power optimization. The choice of the algorithm used can impact the power cost since it determines the runtime complexity of a program. This issue is explored in [24]. It has been noted that the order of instructions can also have an impact on power since it determines the internal switching in the CPU.

CAD Methodologies and Technique: Today's EDA tools effectively support these power- management techniques [25]. They also provide additional power savings during implementation. Low power VLSI designs can be achieved at various levels of the design abstraction from algorithmic and system levels down to layout and circuit levels.

IV. CONCLUSION

High power consumption not only leads to short battery life for hand-held devices but also causes on-chip thermal and reliability problems in general. The need for lower power systems is being driven by many market segments. As application demands increase toward more power sensitive devices, new and novel approaches are needed to meet those demands. Several of these techniques can be used in unison to provide the lowest power solution possible. Sleep mode, clock gating, power gating, gate level optimizations, low power libraries, low power architectures and voltage scaling are all proven low power techniques and should be considered when architecting any new application. Designing for low power adds another dimension to the already complex design problem; the design has to be optimized for Power as well as Performance and Area. Optimizing the three axes necessitates a new class of power conscious CAD tools.

We have surveyed power optimizations applicable at various levels of abstraction, Lowering power dissipation at all abstraction levels is a focus of intense academic and industrial research. These methods are being incorporated into state-of-the-art Computer-Aided Design frameworks.

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